

RF 2969 MOD 7 A/B KIT

RF 2969 Mod 7 is a room temperature curing, electrically conductive epoxy resin system. RF 2969 Mod 7 provides excellent adhesive performance and high electrical and thermally conductive properties. Mod 7 has a higher viscosity and a shorter thin film set time than Mod 4. This material is designed where hot solder applications are impractical or on parts which cannot be subjected to heat. RF 2969 Mod 7 is also effective as a shielding material.



HANDLING PROPERTIES, TYPICAL

PROPERTY	RF 2969
Mix Ratio: by Weight	100:50
by Volume	2:1
Mixed Color	Silver
Mixed Viscosity @ 77°F (25°C)	300,000 (Thixotropic)
Pot Life, 100 grams @ 77°F (25°C)	60 min
Cure Schedule	5-7 Days @ 25°C or 4 Hours @ 65°C

POPULAR FOR USE IN: ELECTRONICS ELECTRIC VEHICLE AEROSPACE

USES & APPLICATIONS

RF 2969 is suitable for electrical circuit connections, grounding of composites or hardware, static dissipation, and RFI shielding.

PHYSICAL PROPERTIES, TYPICAL CURED PERFORMANCE

PROPERTY	TEST METHOD	UNIT	VALUE
Al-Al Lap Shear	ASTM D1002	psi	1.80E+03
Cured Hardness		Shore D	+ 08
DSC Tg	ASTM E1356	°C	68
Volume Resistivity	ASTM B193	Ohm-cm	4.50E-03
Stripe Resistance		Ohm	0.38

SPECIALTY PACKAGING AND DISPENSING

Material is suitable for pre-mixed and frozen and bulk packaging use.

LEARN MORE: Download the TDS or SDS from our TDS SDS Library »

COMMITMENT TO QUALITY AND SERVICE

GracoRoberts and Resin Formulators are fully qualified to design, manufacture, and distribute products to a variety of industries.

Certifications:

- ISO9001:2015
- AS9100 (Rev. D)
- AS9120 (Rev. B)